Product / Package Information

Package:	WLCSP
Body Size (mm):	
I/O Count:	144
Terminal Finish:	SnAgCu
Material Set:	MS012355B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	05-Jul-19

Materials Declaration

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.72 E-02	100.00	1000000	79.35	793467

Wafer Bumps

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.46 E-02	96.50	965000	17.28	172831
Tin & its alloys	Silver	7440-22-4	4.55 E-04	3.00	30000	0.54	5373
Tin & its alloys	Copper	7440-50-8	7.59 E-05	0.50	5000	0.09	895
Subtotal			1.52E-02	100.00	1000000	17.91	179099

UBM / Redistribution Layers

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Metal	Titanium	7440-32-6	1.46 E-05	0.96	9588	0.02	173
Metal	Copper	7440-50-8	5.80 E-05	3.80	38011	0.07	684
Metal	Copper	7440-50-8	1.45 E-03	95.24	952401	1.71	17146
Subtotal			1.53 E-03	100.00	1000000	1.80	18003

Polyimide

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Subtotal		Proprietary	7.99E-04	100	1000000	0.94	9431

	Weight (g)	Percentage (%)	PPM
Package Totals	**8.47 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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